molex

Part Number : 879781021

Product Description : 1.00mm Pitch DDR-2 DIMM Socket, Vertical, with Beveled Metal Pins, Very Low Profile Black Latches, 240 Circuits, 1.8V Center Voltage Key, 3.18mm Tail Length, 0.38µm Gold (Au) Plating, Lead-Free

Series Number : 87978

Status : Obsolete

Product Category : Memory Module Connectors

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	ⓔ
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Obsolete
Category	Memory Module Connectors
Series	87978
Description	1.00mm Pitch DDR-2 DIMM Socket, Vertical, with Beveled Metal Pins, Very Low Profile Black Latches, 240 Circuits, 1.8V Center Voltage Key, 3.18mm Tail Length, 0.38µm Gold (Au) Plating, Lead-Free
Component Type	Socket
JEDEC Outline	MO-237
Product Family	Memory Module Sockets
Product Name	DDR2 DIMM
UPC	822350307147

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Voltage Key	1.8V, Center
Voltage - Maximum	30V

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	Vertical (Top Entry)
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Black
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic

Net Weight	9.330/g
Packaging Type	Tray
PC Tail Length	3.18mm
PCB Retention	Yes
PCB Thickness - Recommended	2.40mm
Pitch - Mating Interface	1.00mm
Plating min - Mating	0.381μm
Plating min - Termination	2.540μm
Temperature Range - Operating	-10° to +85°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	WAVE
Max-Cycle	1
Max-Temp	265

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